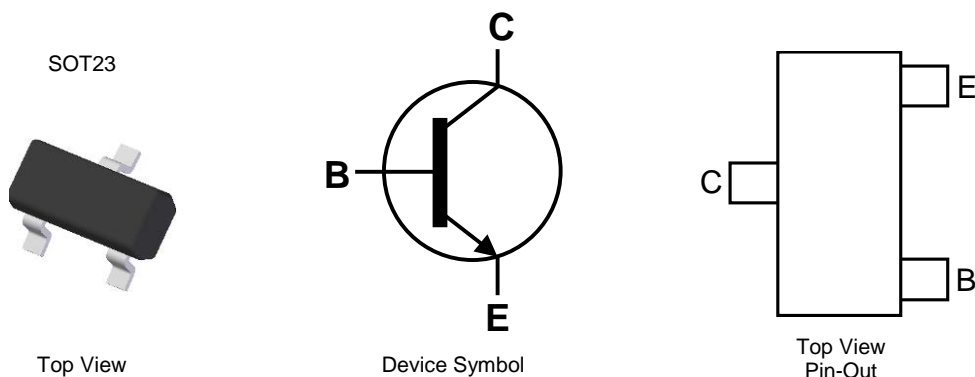


## Features

- Epitaxial Planar Die Construction
- Complementary PNP Type: MMBT2907A
- Ideal for Low Power Amplification and Switching
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

## Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (Approximate)

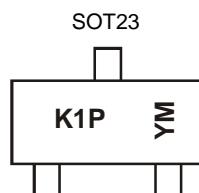


## Ordering Information (Notes 4 & 5)

Product	Status	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMBT2222A-7-F	Active	AEC-Q101	K1P	7	8	3,000
MMBT2222A-13-F	Active	AEC-Q101	K1P	13	8	10,000
MMBT2222AQ-7-F	Active	Automotive	K1P	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to [http://www.diodes.com/product\\_compliance\\_definitions.html](http://www.diodes.com/product_compliance_definitions.html).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



K1P = Product Type Marking Code  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: D = 2016)  
 M or  $\bar{M}$  = Month (ex: 9 = September)

### Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024
Code	C	D	E	F	G	H	I	J	K	L

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	75	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current	I <sub>C</sub>	600	mA
Peak Collector Current	I <sub>CM</sub>	800	mA
Peak Base Current	I <sub>BM</sub>	200	mA

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

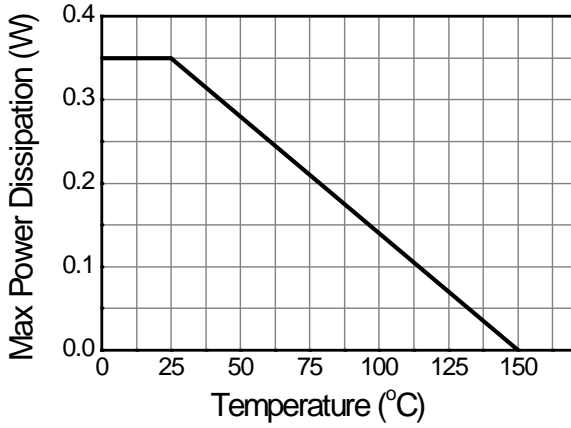
Characteristic	Symbol	Value	Unit
Collector Power Dissipation	P <sub>D</sub>	(Note 6) 310	mW
		(Note 7) 350	
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	(Note 6) 403	°C/W
		(Note 7) 357	
Thermal Resistance, Junction to Leads	R <sub>θJL</sub>	350	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**ESD Ratings** (Note 9)

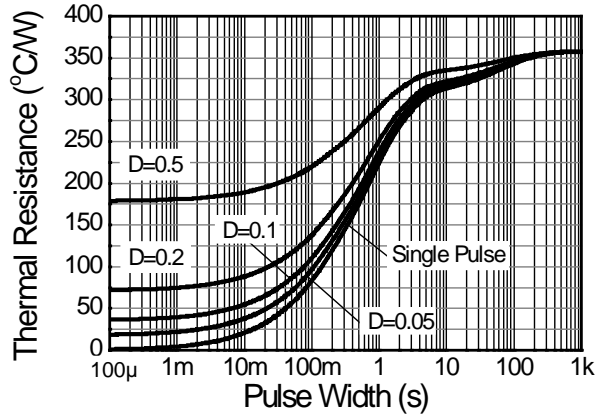
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  7. Same as Note 6, except the device is mounted on 15 mm x 15mm 1oz copper.
  8. Thermal resistance from junction to solder-point (at the end of the leads).
  9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

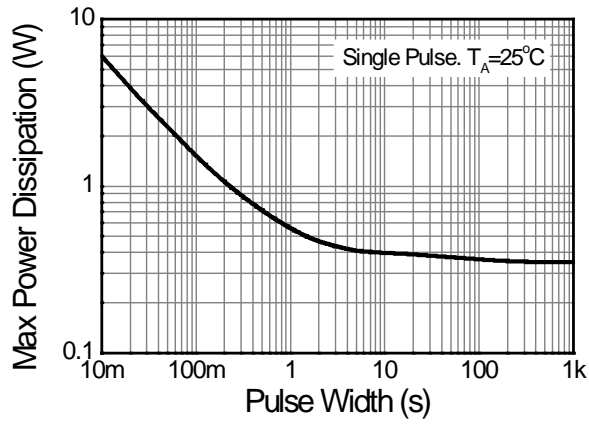
**Thermal Characteristics and Derating Information**



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>					
Collector-Base Breakdown Voltage	BV <sub>CB0</sub>	75	—	V	I <sub>C</sub> = 100μA, I <sub>E</sub> = 0
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	40	—	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	BV <sub>EB0</sub>	6.0	—	V	I <sub>E</sub> = 100μA, I <sub>C</sub> = 0
Collector Cut-Off Current	I <sub>CB0</sub>	—	10	nA μA	V <sub>CB</sub> = 60V, I <sub>E</sub> = 0 V <sub>CB</sub> = 60V, I <sub>E</sub> = 0, T <sub>A</sub> = +150°C
Collector Cut-Off Current	I <sub>CEX</sub>	—	10	nA	V <sub>CE</sub> = 60V, V <sub>EB(OFF)</sub> = 3.0V
Collector Cut-Off Current	I <sub>CEV</sub>	—	10	nA	V <sub>CE</sub> = 60V, V <sub>BE</sub> = ±0.25V
Emitter Cut-Off Current	I <sub>EBO</sub>	—	10	nA	V <sub>EB</sub> = 5.0V, I <sub>C</sub> = 0
Base Cut-Off Current	I <sub>BL</sub>	—	20	nA	V <sub>CE</sub> = 60V, V <sub>EB(OFF)</sub> = 3.0V
<b>ON CHARACTERISTICS (Note 10)</b>					
DC Current Gain	h <sub>FE</sub>	35	—	—	I <sub>C</sub> = 100μA, V <sub>CE</sub> = 10V I <sub>C</sub> = 1.0mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 150mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 500mA, V <sub>CE</sub> = 10V I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10V, T <sub>A</sub> = -55°C I <sub>C</sub> = 150mA, V <sub>CE</sub> = 1.0V
		50	—		
		75	—		
		100	300		
		40	—		
		50	—		
35	—				
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	—	0.3 1.0	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.6 —	1.2 2.0	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	C <sub>obo</sub>	—	8	pF	V <sub>CB</sub> = 10V, f = 1.0MHz, I <sub>E</sub> = 0
Input Capacitance	C <sub>ibo</sub>	—	25	pF	V <sub>EB</sub> = 0.5V, f = 1.0MHz, I <sub>C</sub> = 0
Current Gain-Bandwidth Product	f <sub>T</sub>	300	—	MHz	V <sub>CE</sub> = 20V, I <sub>C</sub> = 20mA, f = 100MHz
Noise Figure	N <sub>F</sub>	—	4.0	dB	V <sub>CE</sub> = 10V, I <sub>C</sub> = 100μA, R <sub>S</sub> = 1.0kΩ, f = 1.0kHz
<b>SWITCHING CHARACTERISTICS</b>					
Delay Time	t <sub>D</sub>	—	10	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA, V <sub>BE(OFF)</sub> = -0.5V, I <sub>B1</sub> = 15mA
Rise Time	t <sub>R</sub>	—	25	ns	V <sub>CC</sub> = 3.0V, I <sub>C</sub> = 150mA, I <sub>B1</sub> = 15mA, V <sub>BE(OFF)</sub> = 0.5V
Storage Time	t <sub>S</sub>	—	225	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA, I <sub>B1</sub> = I <sub>B2</sub> = 15mA
Fall Time	t <sub>F</sub>	—	60	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA, I <sub>B1</sub> = I <sub>B2</sub> = 15mA

Note: 10. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

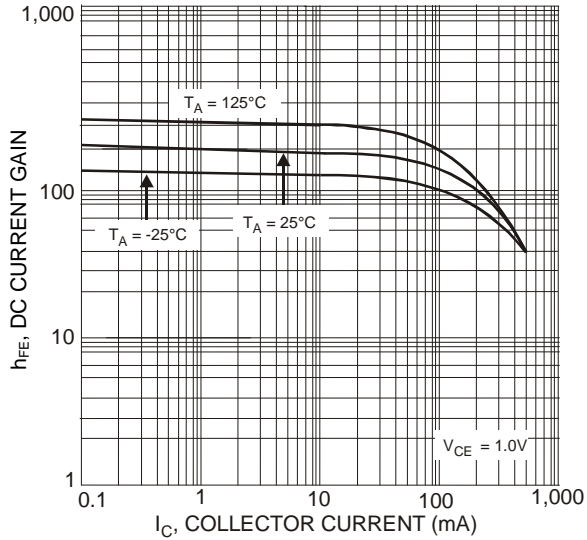


Figure 1 Typical DC Current Gain vs. Collector Current

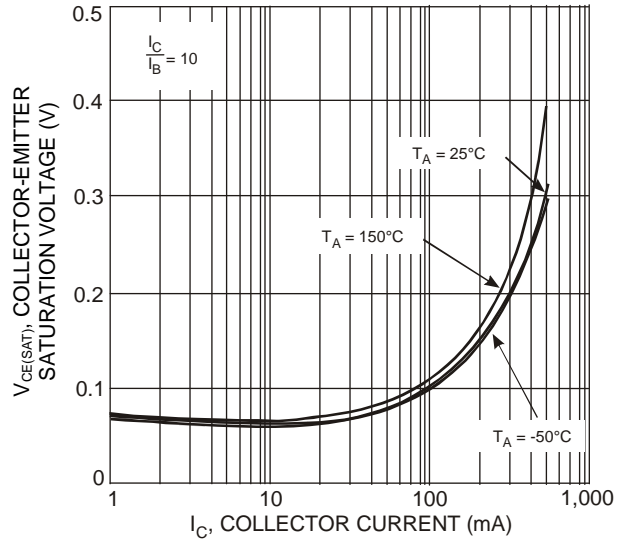


Figure 2 Typical Collector-Emitter Saturation Voltage vs. Collector Current

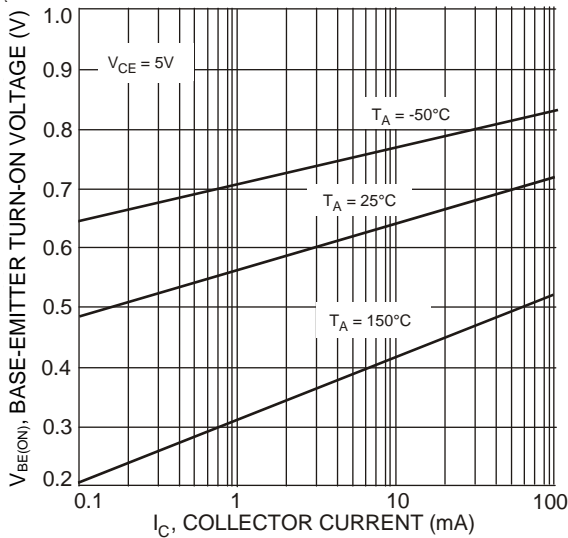


Figure 3 Base-Emitter Turn-On Voltage vs. Collector Current

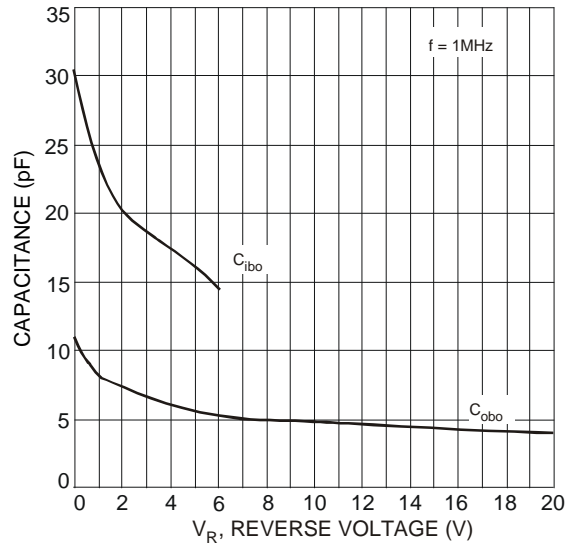


Figure 4 Typical Capacitance Characteristics

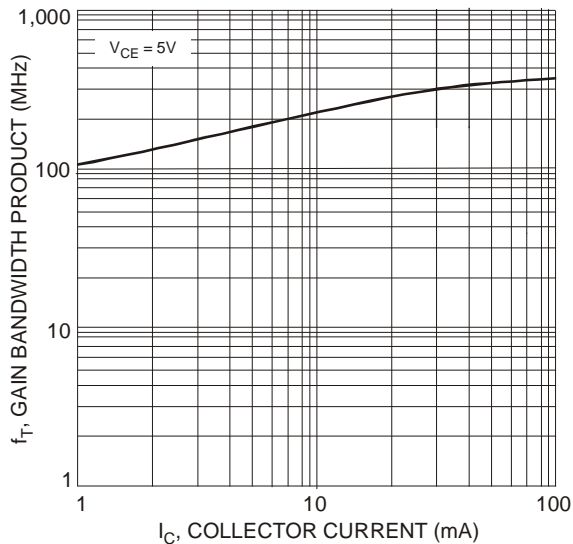


Figure 5 Typical Gain Bandwidth Product vs. Collector Current

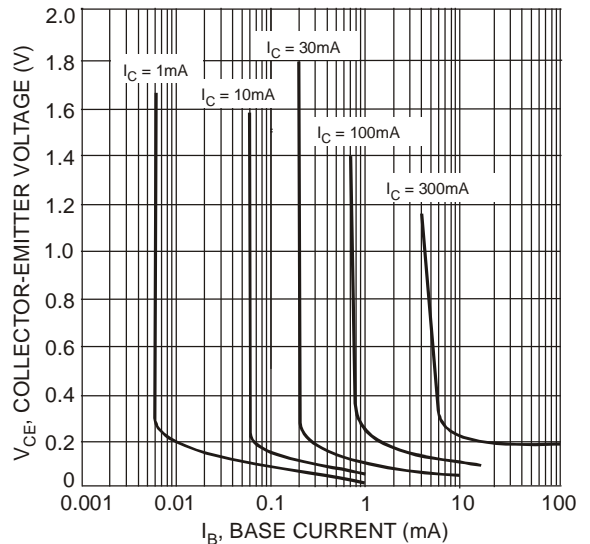
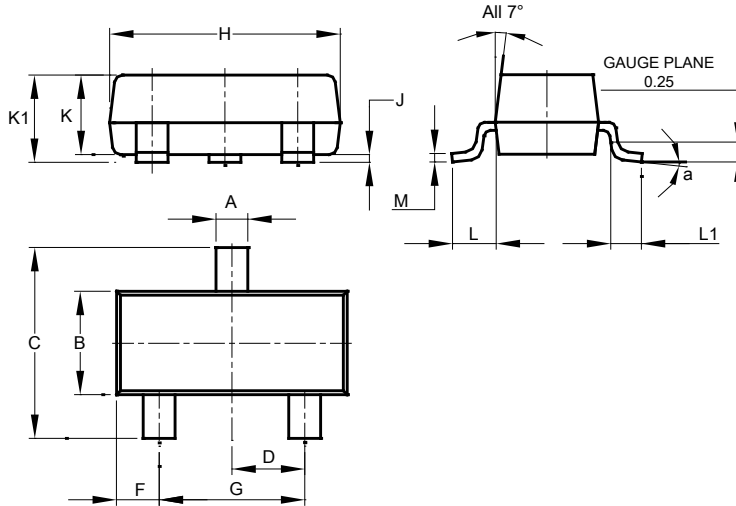


Figure 6 Typical Collector Saturation Region

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**

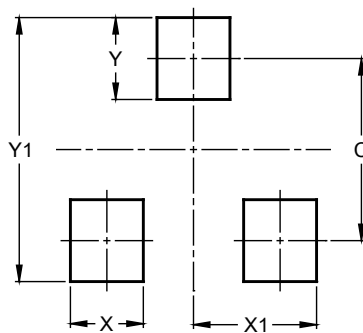


SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**SOT23**



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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